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WHAT IS CLAIMED IS:

1. A light emitting device comprising:

an insulating film over a substrate having a metallic surface;

a light emitting element on the insulating film;

said light emitting element including:

an anode;

a cathode;

an EL material interposed between the anode and the cathode.

2. A light emitting device comprising:

an insulating film over a substrate having a metallic surface;

a light emitting element on the insulating film;

said light emitting element including:

an anode;

a cathode;

an EL material interposed between the anode and the cathode,

wherein a light shielding film is formed in contact with the cathode, or the light shielding film is formed through an insulating film or a conductive film.

3. A device according to claim 1,

wherein the substrate having the metallic surface is a heat resistive metallic substrate.

4. A device according to claim 3,

wherein a thickness of the heat resistive metallic substrate is in a range of 5 μm to 30 μm.

5. A device according to claim 1,

wherein a maximum surface roughness (Rmax) of the substrate is equal to or less than 1 μm.

6. A device according to claim 1,

wherein a radius of curvature of convex portions existing on a surface of the substrate is equal to or greater than 1 μm.

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7. A device according to claim 1,

wherein the light emitting device is one selected from the group consisting of a video camera, a digital camera, a goggle-type display, a navigation system for vehicles, a personal computer, and a portable information terminal.

8. A method of manufacturing a light emitting device, said method comprising the steps of:

bending edge portions of a substrate having a metallic surface;

fixing the substrate to a substrate holder;

forming an insulating film over the substrate having the metallic surface;

forming a light emitting element on the insulating film; and

separating the substrate from the substrate holder.

9. A method according to claim 8,

wherein the fixing step is performed within a vacuum.

10. A method according to claim 8,

wherein the fixing step is performed at a temperature in a range of room

temperature to 400°C.

11. A method according to claim 8, wherein edge portions of the substrate holder have curvature.

12. A method according to claim 8, wherein the substrate holder has a same thermal expansion coefficient as the substrate having the metallic surface.

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13. A method according to claim 8, wherein the substrate having the metallic surface is a heat resistive metallic substrate.

14. A method according to claim 8, wherein a thickness of the heat resistant metallic substrate is in a range of 5 μm to 30 μm.

15. A method according to claim 8, wherein the substrate holder comprises one selected from the group consisting of stainless steel, ceramic and Al_2O_3.

16. A method according to claim 8, wherein the substrate holder has a thickness in a range of 500 μm to 1000 μm.

17. A device according to claim 2, wherein the substrate having the metallic surface is a heat resistive

metallic substrate.

18. A device according to claim 17,

wherein a thickness of the heat resistive metallic substrate is in a range of 5 μm to 30 μm.

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19. A device according to claim 2,

wherein a maximum surface roughness (Rmax) of the substrate is equal to or less than 1 μm.

20. A device according to claim 2,

wherein a radius of curvature of convex portions existing on a surface of the substrate is equal to or greater than 1 μm.

21. A device according to claim 2,

wherein the light emitting device is one selected from the group consisting of a video camera, a digital camera, a goggle-type display, a navigation system for vehicles, a personal computer, and a portable information terminal.

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